

## SNx4AC08 四通道双输入正与门

### 1 特性

- 2V 至 6V  $V_{CC}$  运行
- 输入电压高达 6V
- $t_{pd}$  最大值为 7.5ns (5V 时)

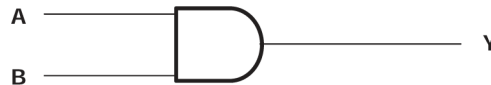
### 2 说明

' AC08 器件是四通道 2 输入正与门。此类器件以正逻辑执行布尔函数  $Y = A \cdot B$ 。

#### 器件信息

器件型号	封装 <sup>(1)</sup>	封装尺寸 <sup>(2)</sup>	本体尺寸 <sup>(3)</sup>
SNx4AC08	BQA ( WQFN , 14 )	3mm x 2.5mm	3mm x 2.5mm
	DB ( SSOP , 14 )	6.2mm x 7.8mm	6.2mm x 5.3mm
	D ( SOIC , 14 )	8.65mm x 6mm	8.65mm x 3.9mm
	N ( PDIP , 14 )	19.3mm x 9.4mm	19.3mm x 6.35mm
	NS ( SO , 14 )	10.2mm x 7.8mm	10.3mm x 5.3mm
	PW ( TSSOP , 14 )	5mm x 6.4mm	5mm x 4.4mm

- (1) 有关更多信息, 请参阅节 10。
- (2) 封装尺寸 (长 × 宽) 为标称值, 并包括引脚 (如适用)。
- (3) 本体尺寸 (长 × 宽) 为标称值, 不包括引脚。



逻辑图, 每个逻辑门 (正逻辑)



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### 3 Pin Configuration and Functions

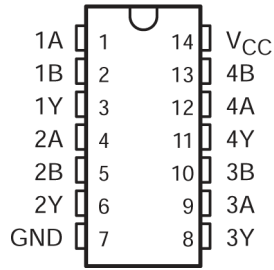


图 3-1. SN54AC08 J or W Package; SN74AC08 D, DB, N, NS, or PW Package (Top View)

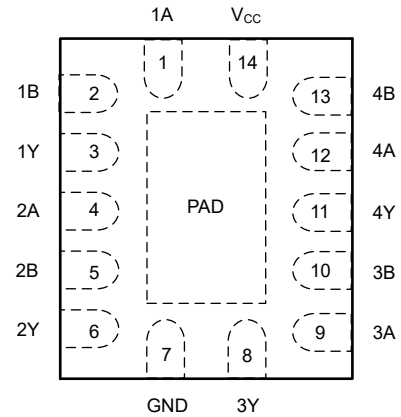
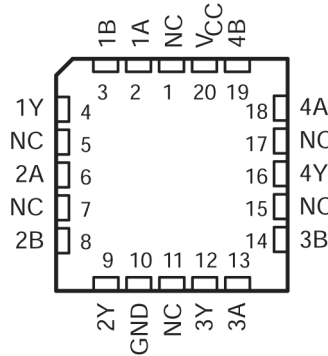


图 3-2. BQA Package, 14-Pin WQFN (Top View)



NC - No internal connection

图 3-3. SN54AC08 FK Package (Top View)

表 3-1. Pin Functions

NAME	PIN		I/O	DESCRIPTION
	D, N, NS, PW, J, or W	FK		
1A	1	2	Input	Channel 1, Input A
1B	2	3	Input	Channel 1, Input B
1Y	3	4	Output	Channel 1, Output Y
2A	4	6	Input	Channel 2, Input A
2B	5	8	Input	Channel 2, Input B
2Y	6	9	Output	Channel 2, Output Y
GND	7	10	—	Ground
3Y	8	12	Output	Channel 3, Output Y
3A	9	13	Input	Channel 3, Input A
3B	10	14	Input	Channel 3, Input B
4Y	11	16	Output	Channel 4, Output Y
4A	12	18	Input	Channel 4, Input A
4B	13	19	Input	Channel 4, Input B
V <sub>CC</sub>	14	20	—	Positive Supply

表 3-1. Pin Functions (续)

PIN			I/O	DESCRIPTION
NAME	D, N, NS, PW, J, or W	FK		
NC		1, 5, 7, 11, 15, 17	—	Not internally connected

## 4 Specifications

### 4.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage range	-0.5	7	V
$V_I$ <sup>(2)</sup>	Input voltage range	-0.5	$V_{CC} + 0.5$	V
$V_O$ <sup>(2)</sup>	Output voltage range	-0.5	$V_{CC} + 0.5$	V
$I_{IK}$	Input clamp current	$(V_I < 0 \text{ or } V_I > V_{CC})$		$\pm 20$ mA
$I_{OK}$	Output clamp current	$(V_O < 0 \text{ or } V_O > V_{CC})$		$\pm 20$ mA
$I_O$	Continuous output current	$(V_O = 0 \text{ to } V_{CC})$		$\pm 50$ mA
	Continuous current through $V_{CC}$ or GND			$\pm 200$ mA
$T_{stg}$	Storage temperature range	-65	150	°C

(1) Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

### 4.2 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		SN54AC08		SN74AC08		UNIT
		MIN	MAX	MIN	MAX	
$V_{CC}$	Supply voltage	2	6	2	6	V
$V_{IH}$	High-level input voltage	$V_{CC} = 3V$	2.1	2.1		V
		$V_{CC} = 4.5V$	3.15	3.15		
		$V_{CC} = 5.5V$	3.85	3.85		
$V_{IL}$	Low-level input voltage	$V_{CC} = 3V$	0.9		0.9	V
		$V_{CC} = 4.5V$	1.35		1.35	
		$V_{CC} = 5.5V$	1.65		1.65	
$V_I$	Input voltage	0	$V_{CC}$	0	$V_{CC}$	V
$V_O$	Output voltage	0	$V_{CC}$	0	$V_{CC}$	V
$I_{OH}$	High-level output current	$V_{CC} = 3V$	-12		-12	mA
		$V_{CC} = 4.5V$	-24		-24	
		$V_{CC} = 5.5V$	-24		-24	
$I_{OL}$	Low-level output current	$V_{CC} = 3V$	12		12	mA
		$V_{CC} = 4.5V$	24		24	
		$V_{CC} = 5.5V$	24		24	
$\Delta t/\Delta v$	Input transition rise or fall rate	8		8		ns/V
$T_A$	Operating free-air temperature	-55	125	-40	85	°C

(1) All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

### 4.3 Thermal Information

THERMAL METRIC <sup>(1)</sup>		SNx4AC08						UNIT
		BQA (WQFN)	D (SOIC)	DB (SSOP)	N (PDIP)	NS (SOP)	PW (TSSOP)	
		14 PINS	14 PINS	14 PINS	14 PINS	14 PINS	14 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	91.3	119.9	96	80	76	145.7	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

### 4.4 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	$V_{CC}$	$T_A = 25^\circ\text{C}$			SN54AC08		SN74AC08		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$V_{OH}$	$I_{OH} = -50 \mu\text{A}$	3V	2.9			2.9		2.9	V	
		4.5V	4.4			4.4		4.4		
		5.5V	5.4			5.4		5.4		
	$I_{OH} = -12 \text{ mA}$	3V	2.56			2.4		2.46		
		4.5V	3.86			3.7		3.76		
	$I_{OH} = -24 \text{ mA}$	5.5V	4.86			4.7		4.76		
		$I_{OH} = -50 \text{ mA}^{(1)}$	5.5V				3.85			
$I_{OH} = -75 \text{ mA}^{(1)}$	5.5V						3.85			
$V_{OL}$	$I_{OL} = 50 \mu\text{A}$	3V	0.002	0.1		0.1		0.1	V	
		4.5V	0.001	0.1		0.1		0.1		
		5.5V	0.001	0.1		0.1		0.1		
	$I_{OL} = 12 \text{ mA}$	3V			0.36		0.5	0.44		
		4.5V			0.36		0.5	0.44		
	$I_{OL} = 24 \text{ mA}$	5.5V			0.36		0.5	0.44		
		$I_{OL} = 50 \text{ mA}^{(1)}$	5.5V				1.65			
$I_{OL} = 75 \text{ mA}^{(1)}$	5.5V						1.65			
$I_I$	A or B ports	$V_I = V_{CC}$ or GND	5.5V		$\pm 0.1$		$\pm 1$	$\pm 1$	$\mu\text{A}$	
$I_{CC}$	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5V			2		40	20	$\mu\text{A}$	
$C_i$	$V_I = V_{CC}$ or GND	5V			4.5				pF	

(1) Not more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.

### 4.5 Switching Characteristics, $V_{CC} = 3.3\text{V} \pm 0.3\text{V}$

over recommended operating free-air temperature range,  $V_{CC} = 3.3\text{V} \pm 0.3\text{V}$  (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$			SN54AC08		SN74AC08		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$t_{PLH}$	A or B	Y	1.5	7.5	9.5	1	12.5	1	10	ns
$t_{PHL}$			1.5	7	8.5	1	11.5	1	9	

#### 4.6 Switching Characteristics, $V_{CC} = 5V \pm 0.5V$

over recommended operating free-air temperature range,  $V_{CC} = 5V \pm 0.5V$  (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

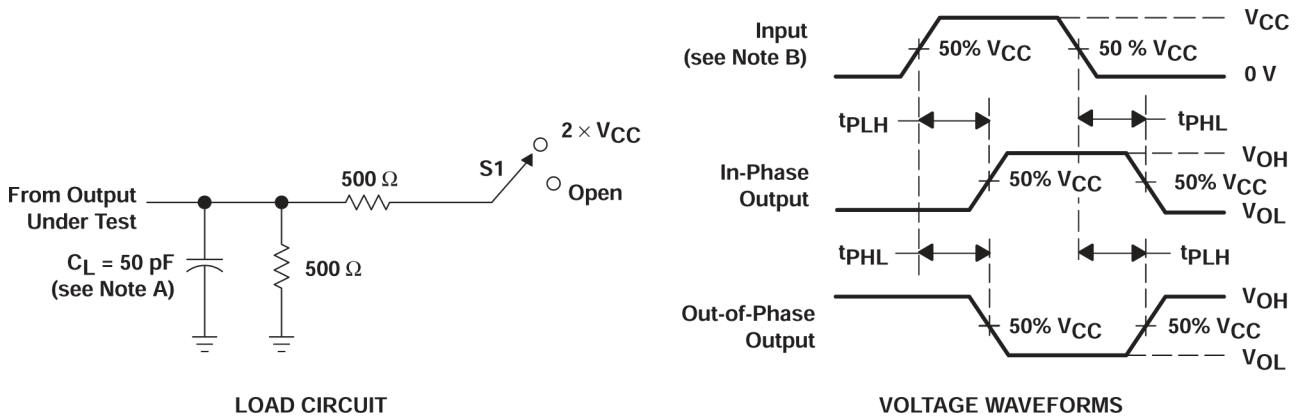
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$			SN54AC08		SN74AC08		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$t_{PLH}$	A or B	Y	1.5	5.5	7.5	1	9	1	8.5	ns
$t_{PHL}$			1.5	5.5	7	1	8.5	1	7.5	

#### 4.7 Operating Characteristics

$V_{CC} = 5V$ ,  $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	TYP	UNIT
$C_{pd}$	Power dissipation capacitance	$C_L = 50\text{ pF}$ , $f = 1\text{ MHz}$	20	pF

## 5 Parameter Measurement Information



- A.  $C_L$  includes probe and jig capacitance.
- B. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r \leq 2.5 \text{ ns}$ ,  $t_f \leq 2.5 \text{ ns}$ .
- C. The outputs are measured one at a time with one input transition per measurement.

图 5-1. Load Circuit and Voltage Waveforms

TEST	S1
$t_{PLH}/t_{PHL}$	Open



## 6 Detailed Description

### 6.1 Functional Block Diagram

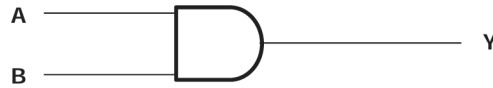


图 6-1. Logic Diagram, Each Gate (Positive Logic)

### 6.2 Device Functional Modes

表 6-1. Function Table (Each Gate)

INPUTS		OUTPUT Y
A	B	
H	H	H
L	X	L
X	L	L

## 7 Application and Implementation

### 备注

以下应用部分中的信息不属于 TI 器件规格的范围，TI 不担保其准确性和完整性。TI 的客户应负责确定器件是否适用于其应用。客户应验证并测试其设计，以确保系统功能。

### 7.1 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the [Recommended Operating Conditions](#). Each  $V_{CC}$  terminal should have a bypass capacitor to prevent power disturbance. A 0.1- $\mu$ F capacitor is recommended for this device. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. The 0.1- $\mu$ F and 1- $\mu$ F capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results.

### 7.2 Layout

#### 7.2.1 Layout Guidelines

When using multiple-input and multiple-channel logic devices inputs must not ever be left floating. In many cases, functions or parts of functions of digital logic devices are unused; for example, when only two inputs of a triple-input AND gate are used. Such unused input pins must not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. All unused inputs of digital logic devices must be connected to a logic high or logic low voltage, as defined by the input voltage specifications, to prevent them from floating. The logic level that must be applied to any particular unused input depends on the function of the device. Generally, the inputs are tied to GND or  $V_{CC}$ , whichever makes more sense for the logic function or is more convenient.

#### 7.2.2 Layout Example

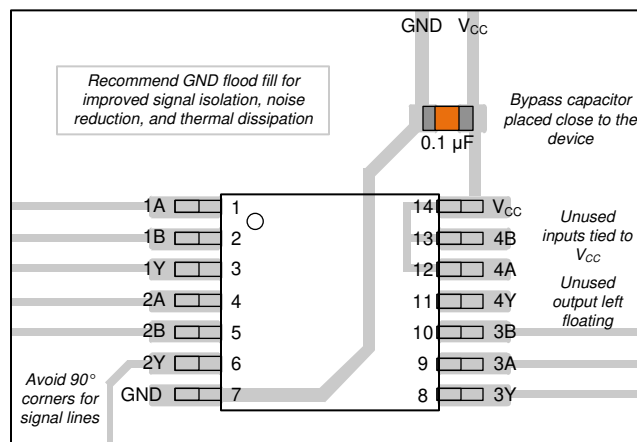


图 7-1. Example layout for the SN74AC08

## 8 Device and Documentation Support

### 8.1 Documentation Support (Analog)

#### 8.1.1 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
SN54AC08	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>
SN74AC08	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>

### 8.2 接收文档更新通知

要接收文档更新通知，请导航至 [ti.com](http://ti.com) 上的器件产品文件夹。点击 [通知](#) 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

### 8.3 支持资源

TI E2E™ [中文支持论坛](#) 是工程师的重要参考资料，可直接从专家处获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题，获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的 [使用条款](#)。

### 8.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.

所有商标均为其各自所有者的财产。

### 8.5 静电放电警告



静电放电 (ESD) 会损坏这个集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

### 8.6 术语表

[TI 术语表](#) 本术语表列出并解释了术语、首字母缩略词和定义。

## 9 Revision History

注：以前版本的页码可能与当前版本的页码不同

### Changes from Revision E (July 2024) to Revision F (February 2025) Page

- 向 [封装信息表](#)、[引脚配置和功能](#) 部分以及 [热性能信息表](#) 中添加了 BQA 封装..... 1

### Changes from Revision D (October 2003) to Revision E (July 2024) Page

- 添加了 [器件信息表](#)、[引脚功能表](#)、[热性能信息表](#)、[器件功能模式](#)、[应用和实施](#) 部分、[器件和文档支持](#) 部分以及 [机械、封装和可订购信息](#) 部分..... 1
- Updated R<sup>θ</sup> JA values: D = 86 to 119.9, PW = 113 to 145.7, all values in °C/W ..... 6

## 10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-87615012A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-87615012A SNJ54AC 08FK	<a href="#">Samples</a>
5962-8761501CA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8761501CA SNJ54AC08J	<a href="#">Samples</a>
5962-8761501DA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8761501DA SNJ54AC08W	<a href="#">Samples</a>
SN74AC08BQAR	ACTIVE	WQFN	BQA	14	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC08	<a href="#">Samples</a>
SN74AC08D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	-40 to 85	AC08	
SN74AC08DBR	ACTIVE	SSOP	DB	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC08	<a href="#">Samples</a>
SN74AC08DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC08	<a href="#">Samples</a>
SN74AC08N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74AC08N	<a href="#">Samples</a>
SN74AC08NSR	ACTIVE	SOP	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC08	<a href="#">Samples</a>
SN74AC08PW	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI	-40 to 85	AC08	
SN74AC08PWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC08	<a href="#">Samples</a>
SN74AC08PWRG4	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC08	<a href="#">Samples</a>
SNJ54AC08FK	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-87615012A SNJ54AC 08FK	<a href="#">Samples</a>
SNJ54AC08J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8761501CA SNJ54AC08J	<a href="#">Samples</a>
SNJ54AC08W	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8761501DA SNJ54AC08W	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of  $\leq 1000$ ppm threshold. Antimony trioxide based flame retardants must also meet the  $\leq 1000$ ppm threshold requirement.

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**OTHER QUALIFIED VERSIONS OF SN54AC08, SN74AC08 :**

- Catalog : [SN74AC08](#)
  
- Automotive : [SN74AC08-Q1](#), [SN74AC08-Q1](#)
  
- Enhanced Product : [SN74AC08-EP](#), [SN74AC08-EP](#)
  
- Military : [SN54AC08](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Military - QML certified for Military and Defense Applications

## TAPE AND REEL INFORMATION



### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AC08BQAR	WQFN	BQA	14	3000	180.0	12.4	2.8	3.3	1.1	4.0	12.0	Q1
SN74AC08DBR	SSOP	DB	14	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74AC08DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74AC08DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74AC08NSR	SOP	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74AC08PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74AC08PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74AC08PWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74AC08PWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

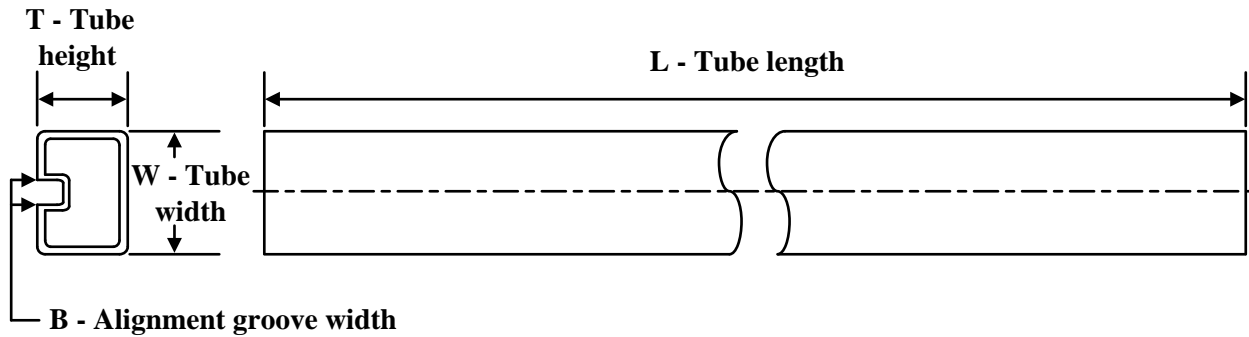


## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AC08BQAR	WQFN	BQA	14	3000	210.0	185.0	35.0
SN74AC08DBR	SSOP	DB	14	2000	356.0	356.0	35.0
SN74AC08DR	SOIC	D	14	2500	353.0	353.0	32.0
SN74AC08DR	SOIC	D	14	2500	356.0	356.0	35.0
SN74AC08NSR	SOP	NS	14	2000	356.0	356.0	35.0
SN74AC08PWR	TSSOP	PW	14	2000	356.0	356.0	35.0
SN74AC08PWR	TSSOP	PW	14	2000	353.0	353.0	32.0
SN74AC08PWRG4	TSSOP	PW	14	2000	356.0	356.0	35.0
SN74AC08PWRG4	TSSOP	PW	14	2000	353.0	353.0	32.0

**TUBE**


\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
5962-87615012A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-8761501DA	W	CFP	14	25	506.98	26.16	6220	NA
SN74AC08N	N	PDIP	14	25	506	13.97	11230	4.32
SN74AC08N	N	PDIP	14	25	506	13.97	11230	4.32
SNJ54AC08FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54AC08W	W	CFP	14	25	506.98	26.16	6220	NA



# D0014A

# PACKAGE OUTLINE

## SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



### NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
5. Reference JEDEC registration MS-012, variation AB.

# EXAMPLE BOARD LAYOUT

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE  
SCALE:8X



SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:8X

4220718/A 09/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

## GENERIC PACKAGE VIEW

**BQA 14**

**WQFN - 0.8 mm max height**

2.5 x 3, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.





4224636/A 11/2018

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for optimal thermal and mechanical performance.

# EXAMPLE BOARD LAYOUT

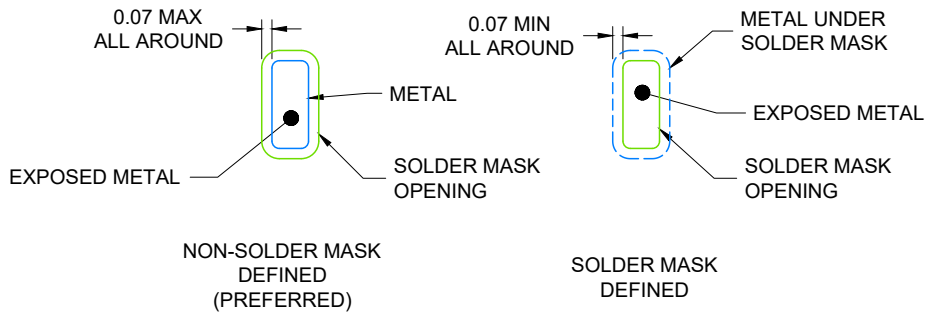
WQFN - 0.8 mm max height

BQA0014A

PLASTIC QUAD FLAT PACK-NO LEAD



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 20X



4224636/A 11/2018

NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/sluea271](http://www.ti.com/lit/sluea271)).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.



# EXAMPLE STENCIL DESIGN

BQA0014A

WQFN - 0.8 mm max height

PLASTIC QUAD FLAT PACK-NO LEAD



SOLDER PASTE EXAMPLE  
 BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD  
 88% PRINTED COVERAGE BY AREA  
 SCALE: 20X

4224636/A 11/2018

NOTES: (continued)

- 6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



4040180-2/F 04/14

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP1-F14

# DB0014A



# PACKAGE OUTLINE

## SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



### NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-150.

# EXAMPLE BOARD LAYOUT

DB0014A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



4220762/A 05/2024

NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DB0014A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220762/A 05/2024

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

## GENERIC PACKAGE VIEW

**FK 20**

**LCCC - 2.03 mm max height**

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



4229370VA\

J 14

**GENERIC PACKAGE VIEW**  
**CDIP - 5.08 mm max height**  
CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4040083-5/G



J0014A



# PACKAGE OUTLINE

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



4214771/A 05/2017

NOTES:

1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.

# EXAMPLE BOARD LAYOUT

J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



LAND PATTERN EXAMPLE  
NON-SOLDER MASK DEFINED  
SCALE: 5X



4214771/A 05/2017

N (R-PDIP-T\*\*)

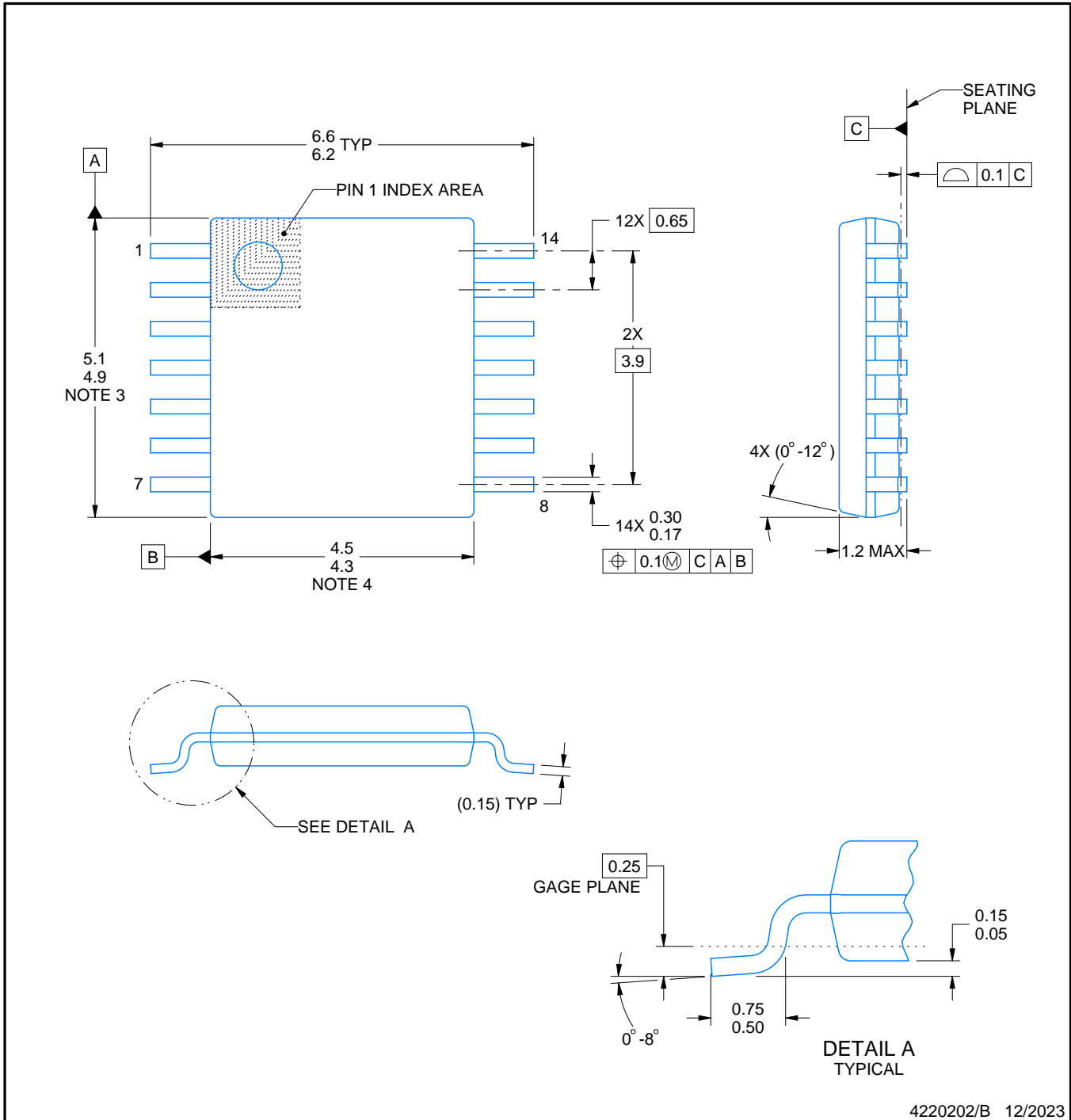
PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - D The 20 pin end lead shoulder width is a vendor option, either half or full width.

4040049/E 12/2002



4220202/B 12/2023

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

# EXAMPLE BOARD LAYOUT

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



4220202/B 12/2023

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220202/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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